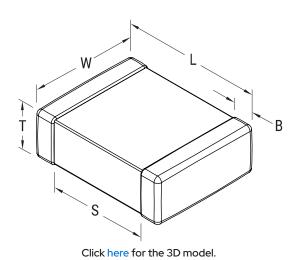




ESD SMD Comm COG, Ceramic, 0.01 uF, 5%, 250 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

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W	1.6mm +/-0.35mm
Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm
Packaging Specifications	

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

0.01 uF
1 kHz 1.0Vrms
5%
250 VDC
25,000 V ESD Level
625 VDC
-55/+125°C
COG
30 ppm/C, 1kHz 1.0Vrms
0.1% 1 kHz 1.0Vrms
0% Loss/Decade Hour
100 GOhms

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